



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20200914001.1

**Qualification of TI Mexico as a new assembly site for select Devices
Change Notification / Sample Request**

Date: September 16, 2020
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services




20200914001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC3200MODR1M2AMOBT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200914001.1	PCN Date:	Sept 16, 2020
Title:	Qualification of TI Mexico as a new assembly site for select Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Dec 16, 2020	Estimated Sample Availability:	Date provided at sample request
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	
PCN Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing the qualification of TI Mexico as a new Assembly site for devices listed below in the product affected section. There are no construction differences between the current and new assembly sites, but there are device symbolization differences as follows:</p>			
	FXC	TI Mexico	
Lid Marking	Sticker Label	Laser Mark	
CC3100MOD Lid Marking sample			
CC3200MOD Lid Marking sample			
Reason for Change:			
Continuity of Supply			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			

Anticipated impact on Material Declaration

<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp
-------------------------------------	---------------------------------------	--------------------------	--

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Foxconn	FXC	CHN	Chongqing
TI Mexico	MEX	MEX	Aguascalientes

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: GHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

CC3100MODR11MAMOB	CC3200MODR1M2AMOB
CC3100MODR11MAMOB	CC3200MODR1M2AMOB

Qualification Report

Approved 14-Sep-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>CC3100MODR11MAMOB</u>	QBS Product Reference: <u>CC3100MODR11MAMOB</u>	QBS Package Reference: <u>CC3235MODSF12MOB</u>
TC	Temperature Cycle, -40/105C	500 Cycles	1/45/0	1/45/0	-
TC	Temperature Cycle, -40/125C	400 Cycles	-	-	1/45/0
UH	Unbiased Temperature and Humidity, 85C/85%RH	500 Hours	1/45/0	1/45/0	-
CDM	ESD CDM	250 V	1/3/0	1/3/0	-
HTSL	High Temp. Storage Bake, 100C	500 Hours	-	1/45/0	-
SD	Solderability	Solderability	-	1/5/0	1/5/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	1/5/0

- QBS: Qualification By Similarity

- Preconditioning was performed for Temperature Cycle, Unbiased Temperature and Humidity, High Temp. Storage Bake, and Biased Temperature and Humidity.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.